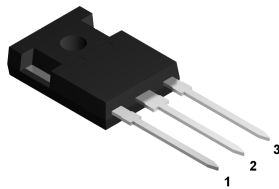
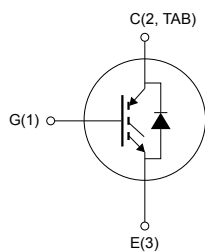


## Trench gate field-stop, 1200 V, 25 A, low-loss, M series IGBT in a TO-247 long leads package



TO-247 long leads



NG1E3C2T



### Product status link

[STGWA25M120DF3](#)

### Product summary

Order code	STGWA25M120DF3
Marking	G25M120DF3
Package	TO-247 long leads
Packing	Tube

### Features

- Maximum junction temperature:  $T_J = 175\text{ °C}$
- 10  $\mu\text{s}$  of short-circuit withstand time
- Low  $V_{CE(sat)} = 1.85\text{ V (typ.) @ } I_C = 25\text{ A}$
- Tight parameter distribution
- Positive  $V_{CE(sat)}$  temperature coefficient
- Low thermal resistance
- Soft- and fast-recovery antiparallel diode

### Applications

- Industrial drives
- UPS
- Solar
- Welding

### Description

This device is an IGBT developed using an advanced proprietary trench gate field-stop structure. The device is part of the M series IGBTs, which represent an optimal balance between inverter system performance and efficiency where the low-loss and the short-circuit functionality is essential. Furthermore, the positive  $V_{CE(sat)}$  temperature coefficient and the tight parameter distribution result in safer paralleling operation.

## 1 Electrical ratings

**Table 1. Absolute maximum ratings**

Symbol	Parameter	Value	Unit
$V_{CES}$	Collector-emitter voltage ( $V_{GE} = 0$ V)	1200	V
$I_C$	Continuous collector current at $T_C = 25$ °C	50	A
	Continuous collector current at $T_C = 100$ °C	25	A
$I_{CP}^{(1)}$	Pulsed collector current	100	A
$V_{GE}$	Gate-emitter voltage	$\pm 20$	V
	Transient gate-emitter voltage	$\pm 30$	V
$I_F$	Continuous forward current at $T_C = 25$ °C	50	A
	Continuous forward current at $T_C = 100$ °C	25	A
$I_{FP}^{(1)}$	Pulsed forward current	100	A
$P_{TOT}$	Total power dissipation at $T_C = 25$ °C	375	W
$T_{STG}$	Storage temperature range	-55 to 150	°C
$T_J$	Operating junction temperature range	-55 to 175	°C

1. Pulse width is limited by maximum junction temperature.

**Table 2. Thermal data**

Symbol	Parameter	Value	Unit
$R_{thJC}$	Thermal resistance junction-case IGBT	0.4	°C/W
	Thermal resistance junction-case diode	0.96	°C/W
$R_{thJA}$	Thermal resistance junction-ambient	50	°C/W

## 2 Electrical characteristics

$T_J = 25\text{ °C}$  unless otherwise specified

**Table 3. Static characteristics**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)CES}$	Collector-emitter breakdown voltage	$V_{GE} = 0\text{ V}, I_C = 2\text{ mA}$	1200			V
$V_{CE(sat)}$	Collector-emitter saturation voltage	$V_{GE} = 15\text{ V}, I_C = 25\text{ A}$		1.85	2.3	V
		$V_{GE} = 15\text{ V}, I_C = 25\text{ A}, T_J = 125\text{ °C}$		2.1		
		$V_{GE} = 15\text{ V}, I_C = 25\text{ A}, T_J = 175\text{ °C}$		2.2		
$V_F$	Forward on-voltage	$I_F = 25\text{ A}$		2.95	4.1	V
		$I_F = 25\text{ A}, T_J = 125\text{ °C}$		2.25		
		$I_F = 25\text{ A}, T_J = 175\text{ °C}$		1.9		
$V_{GE(th)}$	Gate threshold voltage	$V_{CE} = V_{GE}, I_C = 1\text{ mA}$	5	6	7	V
$I_{CES}$	Collector cut-off current	$V_{GE} = 0\text{ V}, V_{CE} = 1200\text{ V}$			25	$\mu\text{A}$
$I_{GES}$	Gate-emitter leakage current	$V_{CE} = 0\text{ V}, V_{GE} = \pm 20\text{ V}$			$\pm 250$	nA

**Table 4. Dynamic characteristics**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$C_{ies}$	Input capacitance	$V_{CE} = 25\text{ V}, f = 1\text{ MHz}, V_{GE} = 0\text{ V}$	-	1550	-	pF
$C_{oes}$	Output capacitance		-	180	-	
$C_{res}$	Reverse transfer capacitance		-	65	-	
$Q_g$	Total gate charge	$V_{CC} = 960\text{ V}, I_C = 25\text{ A},$	-	85	-	nC
$Q_{ge}$	Gate-emitter charge	$V_{GE} = 0\text{ to }15\text{ V}$	-	11.5	-	
$Q_{gc}$	Gate-collector charge	(see Figure 29. Gate charge test circuit)	-	45.5	-	

**Table 5. IGBT switching characteristics (inductive load)**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	$V_{CE} = 600\text{ V}$ , $I_C = 25\text{ A}$ , $V_{GE} = 15\text{ V}$ , $R_G = 15\ \Omega$ (see Figure 28. Test circuit for inductive load switching)		28	-	ns
$t_r$	Current rise time			15	-	ns
$(di/dt)_{on}$	Turn-on current slope			1370	-	A/ $\mu\text{s}$
$t_{d(off)}$	Turn-off delay time			150	-	ns
$t_f$	Current fall time			155	-	ns
$E_{on}^{(1)}$	Turn-on switching energy			0.85	-	mJ
$E_{off}^{(2)}$	Turn-off switching energy			1.3	-	mJ
$E_{ts}$	Total switching energy		2.15	-	mJ	
$t_{d(on)}$	Turn-on delay time	$V_{CE} = 600\text{ V}$ , $I_C = 25\text{ A}$ , $V_{GE} = 15\text{ V}$ , $R_G = 15\ \Omega$ , $T_J = 175\text{ }^\circ\text{C}$ (see Figure 28. Test circuit for inductive load switching)		28	-	ns
$t_r$	Current rise time			17	-	ns
$(di/dt)_{on}$	Turn-on current slope			1270	-	A/ $\mu\text{s}$
$t_{d(off)}$	Turn-off delay time			155	-	ns
$t_f$	Current fall time			240	-	ns
$E_{on}^{(1)}$	Turn-on switching energy			1.6	-	mJ
$E_{off}^{(2)}$	Turn-off switching energy			1.9	-	mJ
$E_{ts}$	Total switching energy		3.5	-	mJ	
$t_{sc}$	Short-circuit withstand time	$V_{CC} \leq 600\text{ V}$ , $V_{GE} = 15\text{ V}$ , $T_{Jstart} \leq 150\text{ }^\circ\text{C}$	10		-	$\mu\text{s}$

1. Including the reverse recovery of the diode
2. Including the tail of the collector current

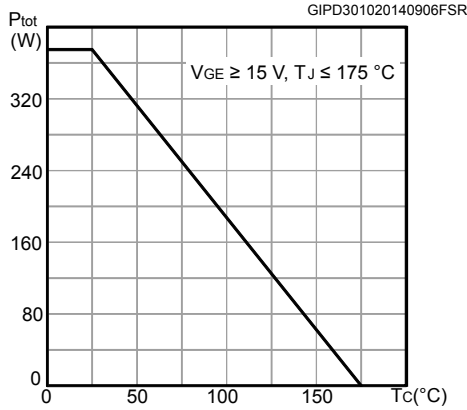
**Table 6. Diode switching characteristics (inductive load)**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit	
$t_{rr}$	Reverse recovery time	$I_F = 25\text{ A}$ , $V_R = 600\text{ V}$ , $V_{GE} = 15\text{ V}$ , $di/dt = 1000\text{ A}/\mu\text{s}$ (see Figure 28. Test circuit for inductive load switching)	-	265	-	ns	
$Q_{rr}$	Reverse recovery charge			-	1.2	-	$\mu\text{C}$
$I_{rrm}$	Reverse recovery current			-	19	-	A
$dI_{rr}/dt$	Peak rate of fall of reverse recovery current during $t_b$			-	1090	-	A/ $\mu\text{s}$
$E_{rr}$	Reverse recovery energy			-	0.22	-	mJ
$t_{rr}$	Reverse recovery time	$I_F = 25\text{ A}$ , $V_R = 600\text{ V}$ , $V_{GE} = 15\text{ V}$ , $T_J = 175\text{ }^\circ\text{C}$ , $di/dt = 1000\text{ A}/\mu\text{s}$ (see Figure 28. Test circuit for inductive load switching)	-	585	-	ns	
$Q_{rr}$	Reverse recovery charge			-	5	-	$\mu\text{C}$
$I_{rrm}$	Reverse recovery current			-	30	-	A
$dI_{rr}/dt$	Peak rate of fall of reverse recovery current during $t_b$			-	270	-	A/ $\mu\text{s}$
$E_{rr}$	Reverse recovery energy			-	0.75	-	mJ

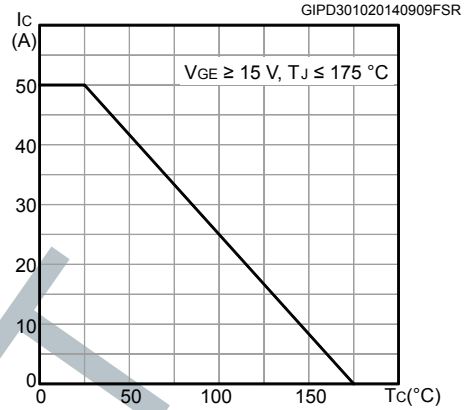


**2.1 Electrical characteristics (curves)**

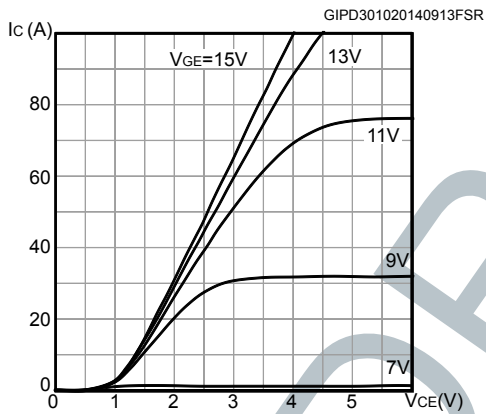
**Figure 1. Power dissipation vs case temperature**



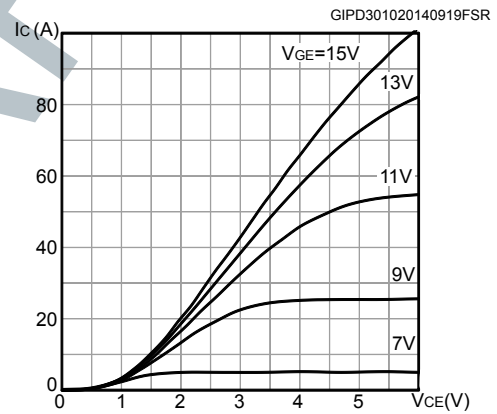
**Figure 2. Collector current vs case temperature**



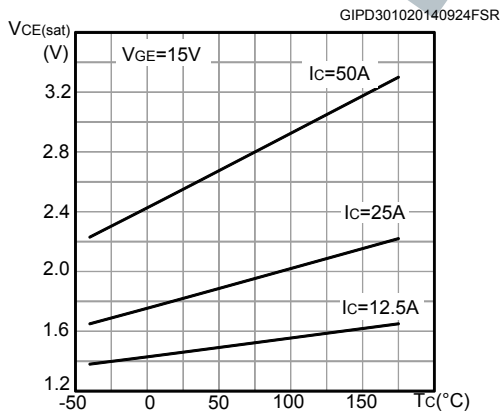
**Figure 3. Output characteristics (T<sub>J</sub> = 25 °C)**



**Figure 4. Output characteristics (T<sub>J</sub> = 175 °C)**



**Figure 5. V<sub>CE(sat)</sub> vs junction temperature**



**Figure 6. V<sub>CE(sat)</sub> vs collector current**

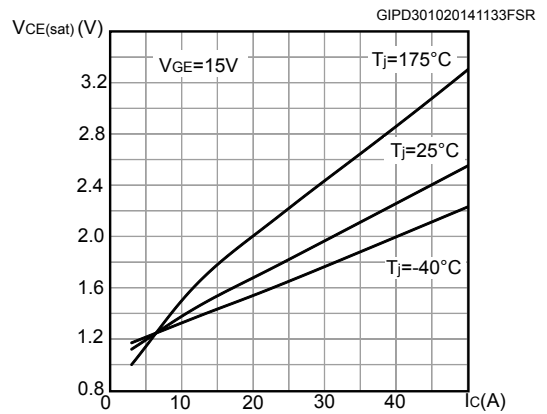




Figure 7. Collector current vs switching frequency

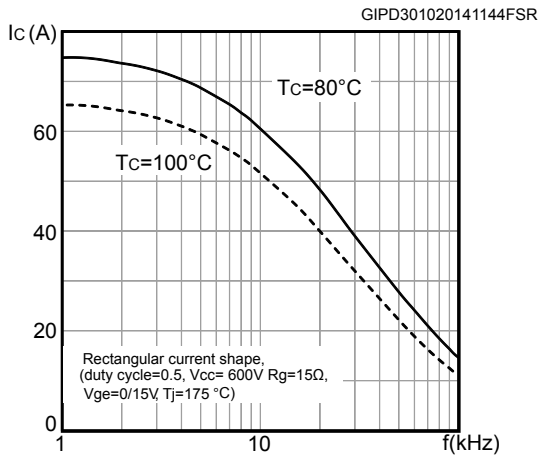


Figure 8. Safe operating area

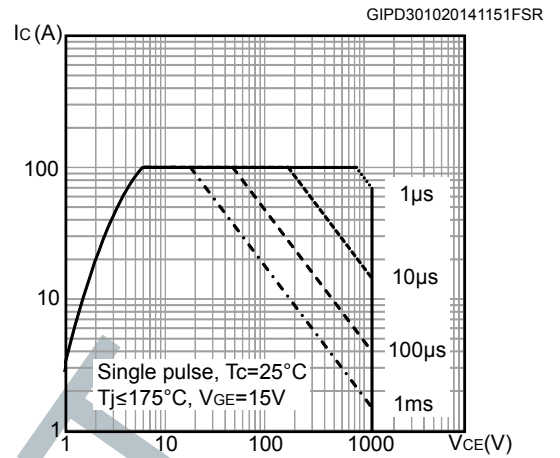


Figure 9. Transfer characteristics

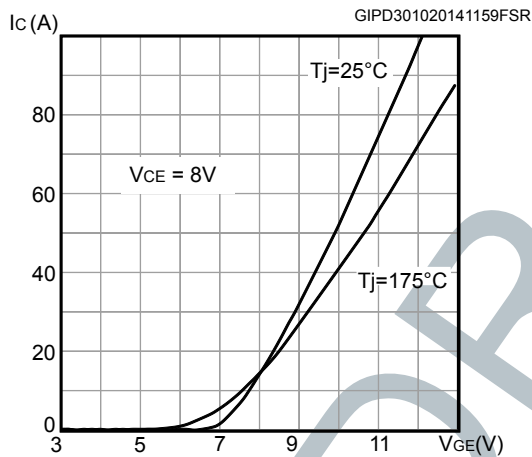


Figure 10. Diode Vf vs forward current

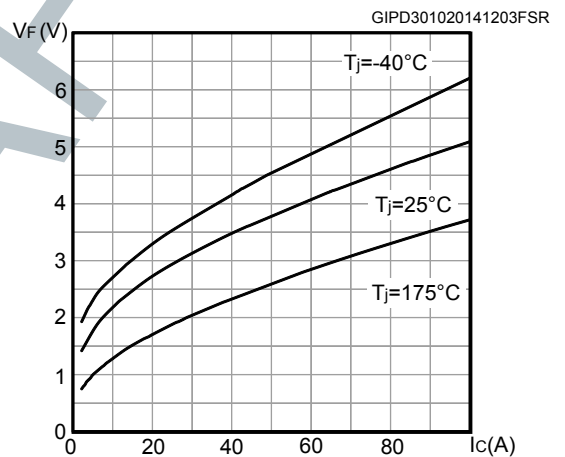


Figure 11. Normalized VGE(th) vs junction temperature

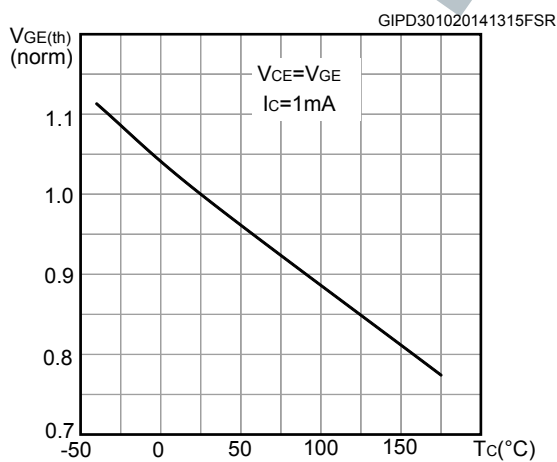


Figure 12. Normalized V(BR)CES vs junction temperature

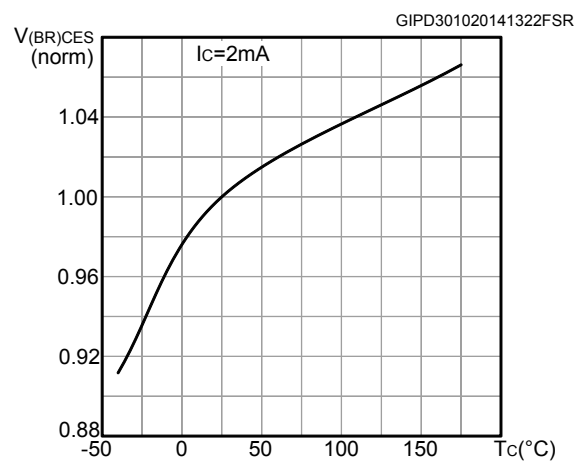




Figure 13. Capacitance variations

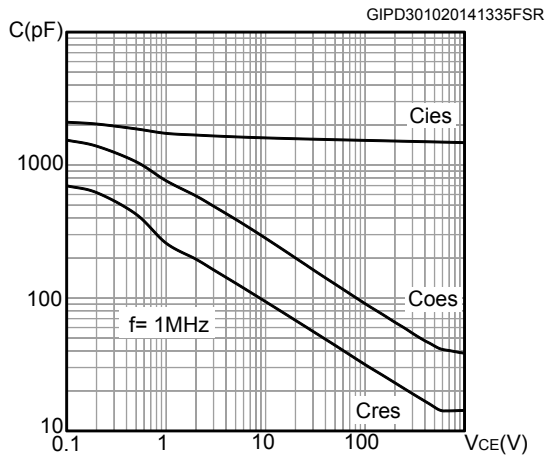


Figure 14. Gate charge vs gate-emitter voltage

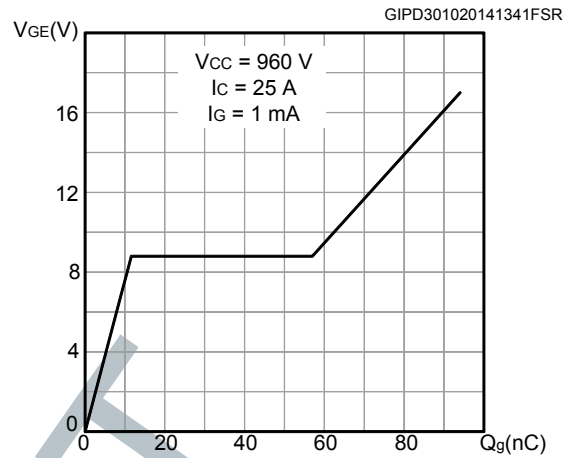


Figure 15. Switching energy vs collector current

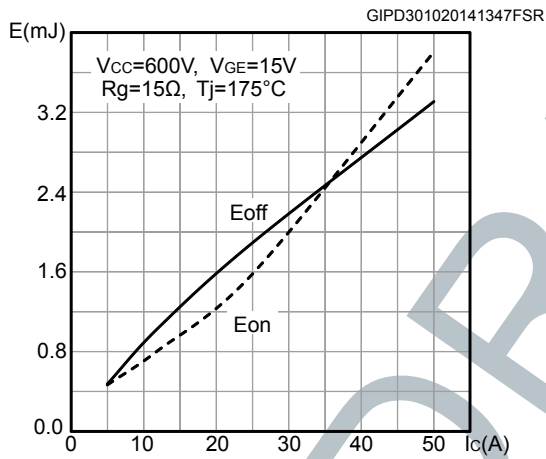


Figure 16. Switching energy vs gate resistance

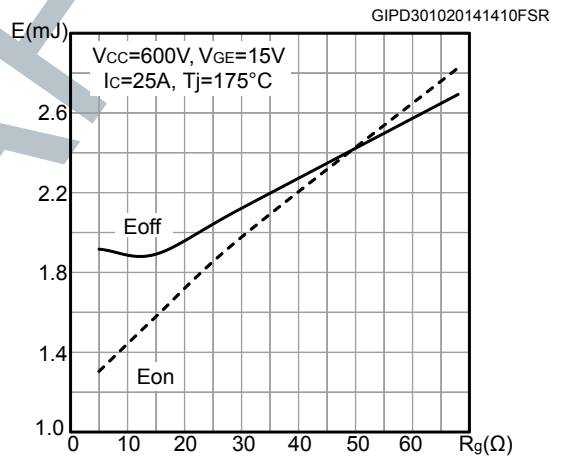


Figure 17. Switching energy vs junction temperature

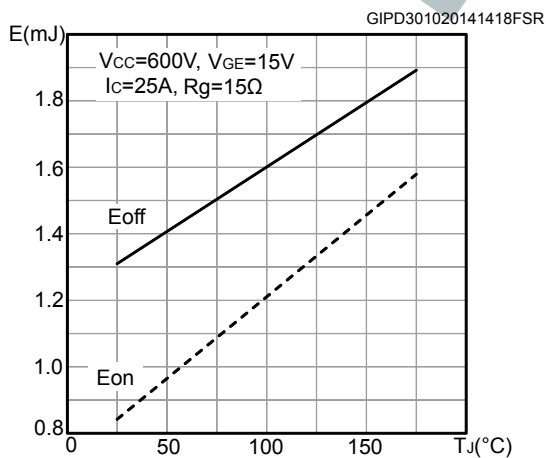


Figure 18. Switching energy vs collector emitter voltage

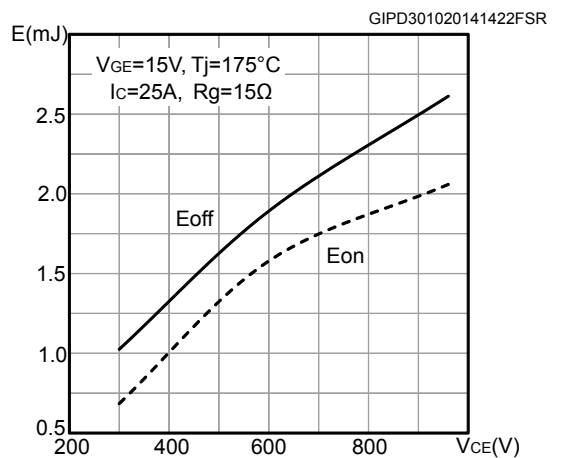




Figure 19. Short-circuit time and current vs  $V_{GE}$

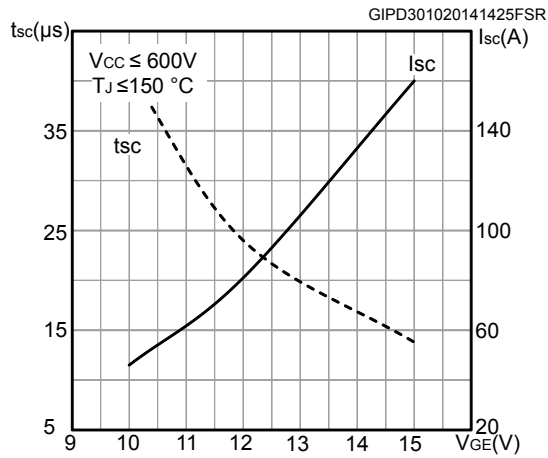


Figure 20. Switching times vs collector current

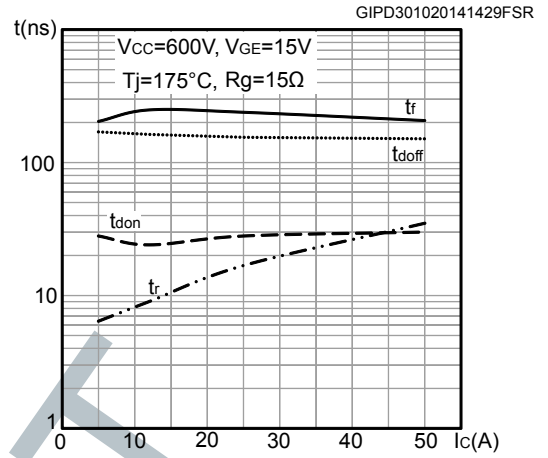


Figure 21. Switching times vs gate resistance

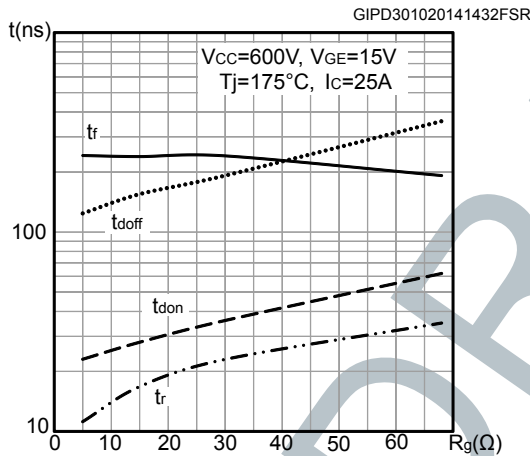


Figure 22. Reverse recovery current vs diode current slope

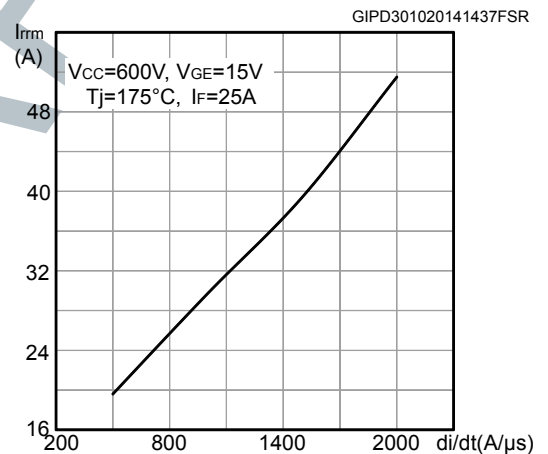


Figure 23. Reverse recovery time vs diode current slope

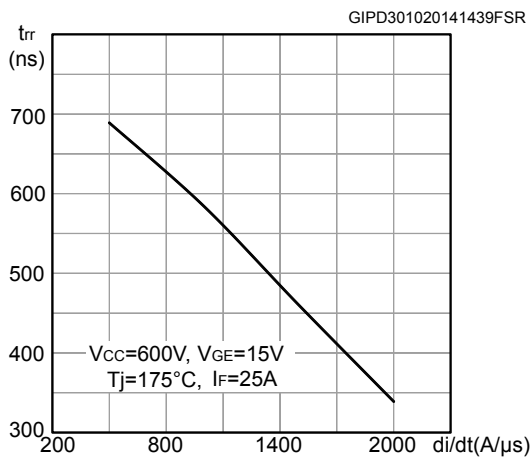


Figure 24. Reverse recovery charge vs diode current slope

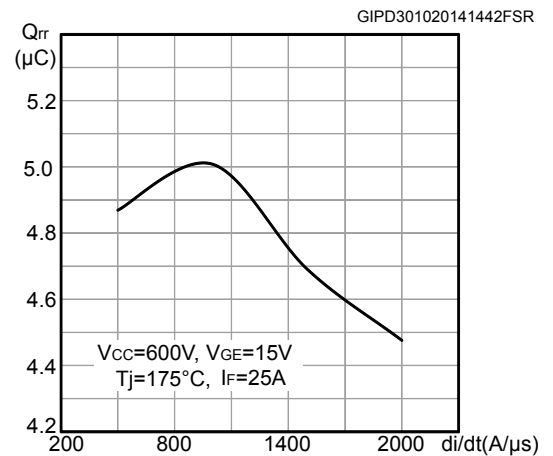




Figure 25. Reverse recovery energy vs diode current slope

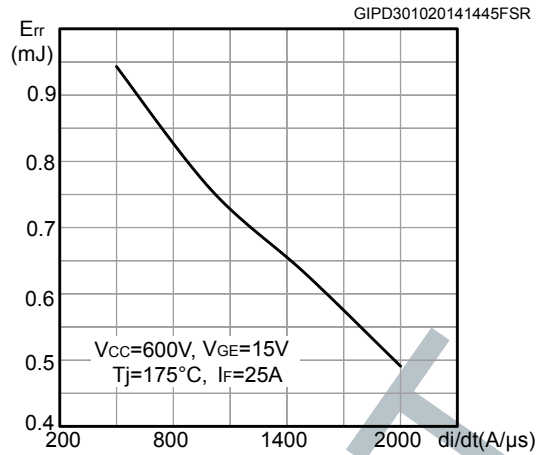


Figure 26. Thermal impedance for IGBT

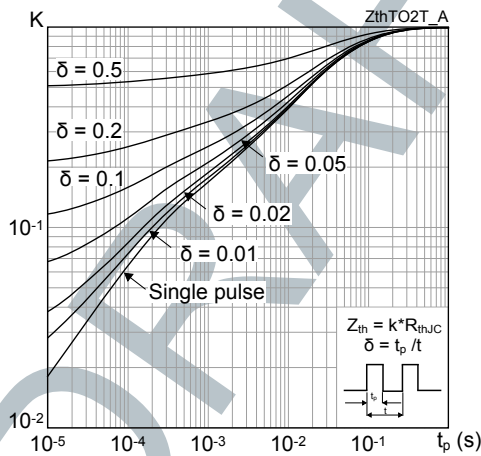
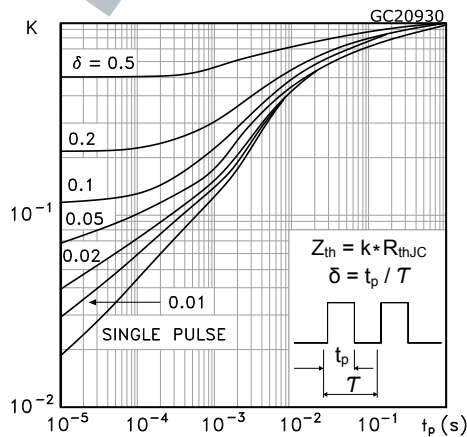


Figure 27. Thermal impedance for diode



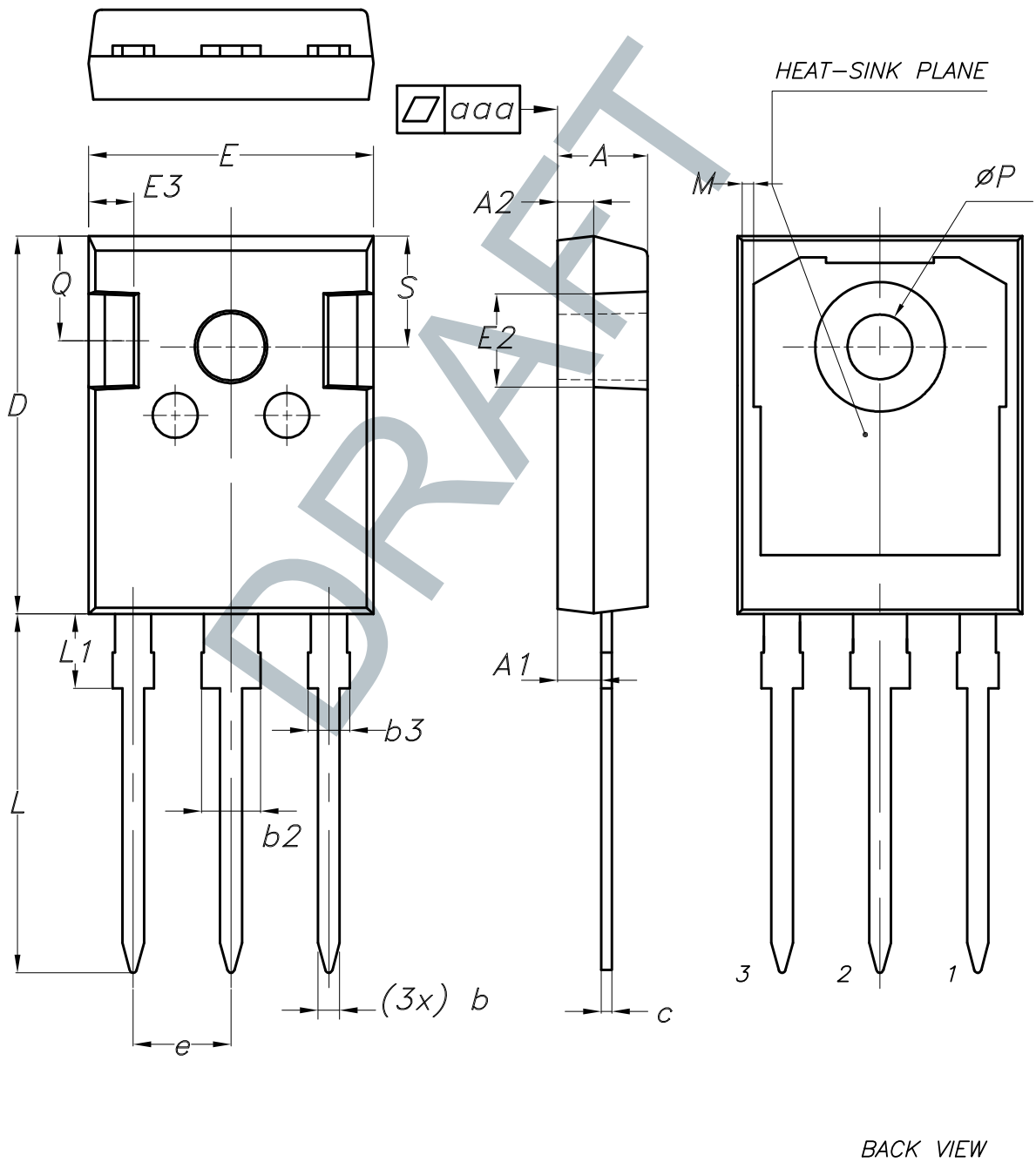


## 4 Package information

To meet environmental requirements, ST offers these devices in different grades of **ECOPACK** packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions, and product status are available at: [www.st.com](http://www.st.com). ECOPACK is an ST trademark.

### 4.1 TO-247 long leads package information

Figure 32. TO-247 long leads package outline



BACK VIEW

8463846\_5


**Table 7. TO-247 long leads package mechanical data**

Dim.	mm		
	Min.	Typ.	Max.
A	4.90	5.00	5.10
A1	2.31	2.41	2.51
A2	1.90	2.00	2.10
b	1.16		1.26
b2			3.25
b3			2.25
c	0.59		0.66
D	20.90	21.00	21.10
E	15.70	15.80	15.90
E2	4.90	5.00	5.10
E3	2.40	2.50	2.60
e	5.34	5.44	5.54
L	19.80	19.92	20.10
L1			4.30
M	0.35		0.95
P	3.50	3.60	3.70
Q	5.60		6.00
S	6.05	6.15	6.25
aaa		0.04	0.10

## Revision history

**Table 8. Document revision history**

Date	Version	Changes
20-Jun-2018	1	Initial release. This part number was previously included in datasheet DS10300.
10-Oct-2024	2	Updated Section 4.1: TO-247 long leads package information. Minor text changes.

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